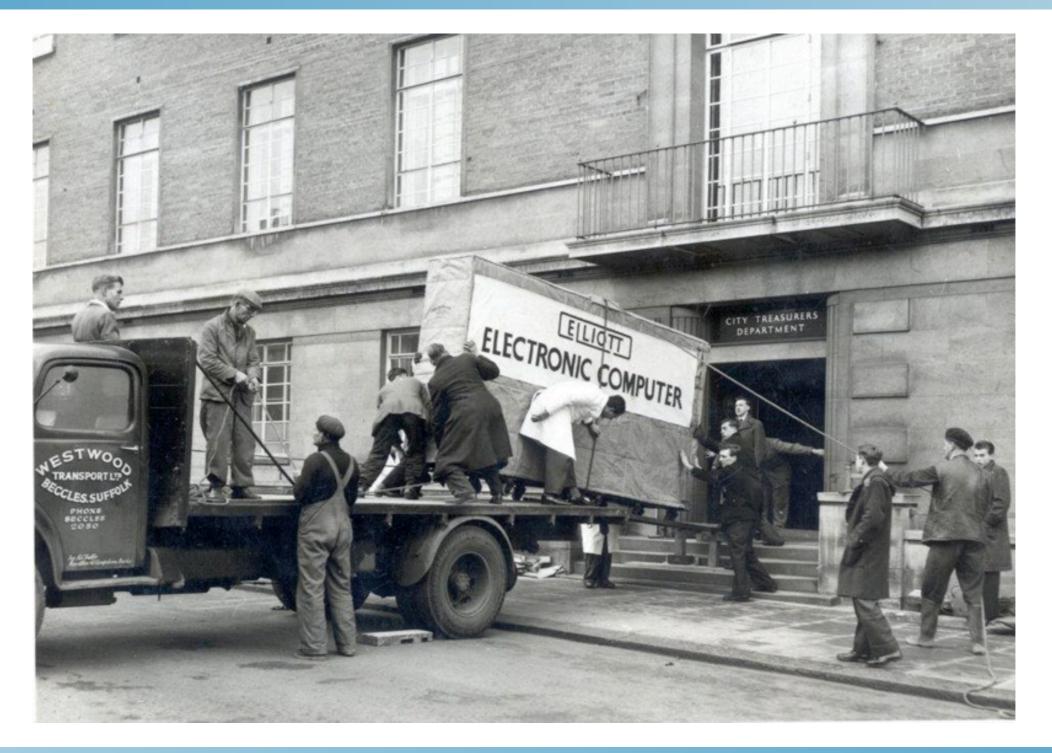
Opportunities in TDAQ



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Opportunities in TDAQ

- The exciting opportunities in this area:
 - Being complex, expensive, and mission-critical
 - Being the first thing in the project to start and the last thing to work
 - Coping with everyone else's random design decisions and changes
 - Only being noticed when the system is broken
- But seriously... there are things to do in 'the back office'
 - DAQ is probably *not* a technical or cost driver for e+e- machines
 - But will be major hassle if not planned correctly from the start witness issues in current upgrade projects
 - DAQ probably is *the* technical and cost driver for hh ($\mu\mu$?) experiments
 - Clear signs that our current approaches will need to change
 - Probably no need for complex pipelined trigger systems
 - Possibly no access to the most advanced technology nodes
 - Strong need to converge to commercial / industrial norms (and to stay current)
- Q: how can the long-term R&D programme benefit our nearer-term projects?
- My definition of DAQ is, all hardware and software involved in:
 - Data selection and movement from front-end devices to off-detector processing and storage
 - Control, configuration, synchronisation and monitoring systems for the detector electronics
 - Real-time or batch computing in the data pipeline before bulk storage
 - NOT analogue / service parts of front-end ASIC (so detector-DAQ boundary is inside the chip)



The Detector Roadmap Sayeth...

			$\begin{array}{c} SOS \\ SOS \\ IF \\ I$										
		DRDT		< 2030			30-2035		2035- 2040	2040-		^(Λ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ^(Δ¹) ⁽	
Data density	High data rate ASICs and systems	7.1	•										
	New link technologies (fibre, wireless, wireline)	7.1			Ĭ							Ŏ.	
	Power and readout efficiency	7.1										Ŏ.	Č
Intelligence on the detector	Front-end programmability, modularity and configurability	7.2										•	
	Intelligent power management	7.2										Ó	Ĩ
	Advanced data reduction techniques (ML/AI)	7.2											
4D- techniques	High-performance sampling (TDCs, ADCs)	7.3											
	High precision timing distribution	7.3					ė 🔶					•	
	Novel on-chip architectures	7.3			Ĭ					Ó		Ŏ	Õ
Extreme environments and longevity	Radiation hardness	7.4			Í							Ŏ	Õ
	Cryogenic temperatures	7.4										ŏ	
	Reliability, fault tolerance, detector control	7.4											
	Cooling	7.4								•		Ŏ •	
Emerging technologies	Novel microelectronic technologies, devices, materials	7.5										Ó	Õ
	Silicon photonics	7.5		_) 🍎 (Ó		Ŏ	Č
	3D-integration and high-density interconnects	7.5								Ŏ		Ó	Ĩ
	Keeping pace with, adapting and interfacing to COTS	7.5	•										Ă

* LHCb Velo

- A lot of this is about capability, expertise and industry engagement
 - Marcus and Mark have covered a lot of the 'how', let's talk about 'what'



Relevance to Future Silicon Projects

• 4D developments

- Need for precise frequency and phase alignment how far can we go?
- Substantially increased data volume per hit
- Requirement / opportunity for local data filtering
- Standardised control and readout we need one each of:
 - 'Slow control' plane (redundant, reliable, simple)
 - Readout L1 protocol (perhaps over multiple physical media)
 - And it had better look like ethernet and use industry-standard data rates
 - Set of verified and exhaustively tested IP blocks to implement this
 - Implementable in either FPGAs or hardened ASICs

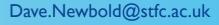
Optimal use of bandwidth

- Sparse events imply intelligent buffering for optimal readout utilisation
 - Readout could easily dominate power requirements in some subdetectors
 - Any properly optimised system will require back pressure all the way to the front end
- Selective / regional / staged / OOO readout may have benefits
 - Implies a more complex handshake between central DAQ and front-end devices
- These statements are all 'trackerish'
 - Issues facing calorimetry are if anything more severe, may need different approaches



Other Cool Stuff for Context

- Possibly not for e+e-, but on the list
 - Timing self-calibration
 - On-chip data reduction and programmable intelligence (ML?)
 - Advanced low-power link technologies
 - Photonic, high-bandwidth galvanic, RF
 - On-detector network (local event building)
 - Smart power management (scalable bandwidth / processing)
 - Novel powering (RF)
- Also many non-collider topics to address
 - Particularly: cryogenic and deep cryogenic electronics
- Setup of an 'Electronics DRD collaboration' now under way
 - Initial discussions between major labs on support and access aspects
 - Expect to re-start community workshops in early 2023?
 - Focussed UK approach is surely needed to underwrite continued leadership
 - There are opportunities (and I hope funding) for those who wish to step up for this





Development Approach

• I argue: we need a standardised DAQ approach from the start

- Recent history of overly complex design with some development failures
 - Approximately 40 different readout ASICs for LHC upgrades; many of them work
 - 'DAQ as a second thought' has now caused major issues in a number of projects
- Standardised approach allows early 'realistic' testing and early development of common control systems (incl. complex real-time software)
- Upfront development of common robust solutions (well before final design) pays off later
- How to approach this?
 - Develop and **model** data pipeline early, rather than focus on sensor / ASIC performance
 - This includes local processing at the front end, but back-end (e.g. trigger) requirements on the front end
 - Target end-to-end demonstrators, minimally ad hoc
 - Consider the 'systems issues' (power, material, space) upfront
- What should the UK do now?
 - Include strong support for 'near term' projects in the overall electronics R&D plan
 - Look again at lessons from LHC (including realistic services estimates)
 - Consider the new capabilities offered by 4D
 - Take leadership in specifying and testing common DAQ interfaces
 - Address modular design issues in and long-term IP reuse across ASIC developments
 - Embed this approach in our tracking and calorimetry prototypes

